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(54) Title: THROUGH SUBSTRATE ANNULAR VIA INCLUDING PLUG FILLER

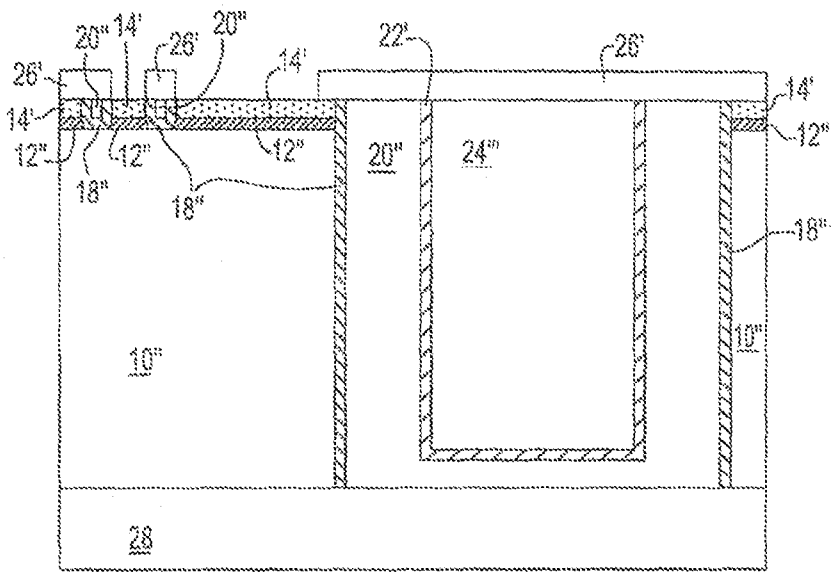


FIG. 13

(57) Abstract: A through substrate (10) via includes an annular conductor layer at a periphery of a through substrate (10) aperture, and a plug layer (24) surrounded by the annular conductor layer. A method for fabricating the through substrate (10) via includes forming a blind aperture within a substrate (10) and successively forming and subsequently planarizing within the blind aperture a conformal conductor layer (20) that does not fill the aperture and plug layer (24) that does fill the aperture. The backside of the substrate (10) may then be planarized to expose at least the planarized conformal conductor layer. (20)

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